

Product Brief



M2-SQ2-xx - Snapdragon based SMARC Module

Using the new SMARC standard 2.0 for embedded modules, TESSOLVEEMBEDDED SYSTEMS introduces ultra-low power ARM COMs (Computer-On-Module) based on the Qualcomm Snapdragon Family which is powered by ARM Cortex-A7 quad-core application CPU. TESSOLVE leverages its vast experience of product development in the area of embedded multimedia systems for professional applications and systems combining audio/video, graphics and HMI.

Target applications for MAGIK2 ARM COMs are HMI units for machines and vehicles, Industrial Tablets, and Multimedia/ Infotainment applications in avionics or transportation environment.

The modules come with a complete software suite with unique differentiators (details below), including Device Drivers, BSP and support for Android 7.1.

TESSOLVE delivers application specific carrier boards along with reference software for related system solutions in the area of HMI units like tablets or similar.

Product development made easy, with the industry leading complete system solution packages from TESSOLVE, is a clear differentiator!

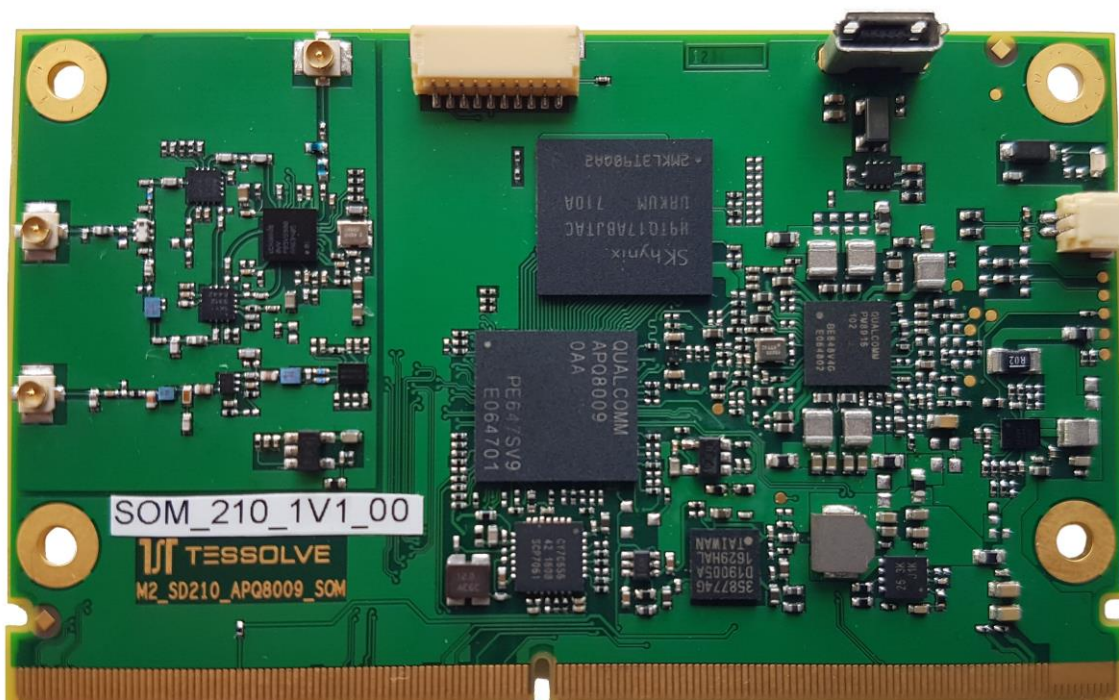


Figure 1: SD210 SOM

The M2-SQ2-xx modules are available in Quad Core CPU with wide variety of IO feature sets.

| | |
|-------------------------|--|
| Technical Information | |
| Module Name | M2-SQ2-4Q |
| Processor | QUALCOMM Snapdragon SD210 <ul style="list-style-type: none"> ARM Cortex-A7 Quad core Upto 1.3 GHz |
| Graphics | <ul style="list-style-type: none"> Adreno 304 GPU; 3D graphics accelerator (up to 409.6 MHz) |
| Memory | <ul style="list-style-type: none"> LPDDR3, upto 2GB (x32 bits) |
| Flash | <ul style="list-style-type: none"> 16GB eMMC 4.5 |
| Display Interface | <ul style="list-style-type: none"> 1x LVDS |
| Camera | <ul style="list-style-type: none"> 1x MIPI CSI (2 lane) 1x MIPI CSI (1 lane) |
| Audio | <ul style="list-style-type: none"> 1x I2S |
| SD/MMC | <ul style="list-style-type: none"> 1x SDIO/MMC(4 bits) |
| Wi-Fi/BT/FM | <ul style="list-style-type: none"> Wi-Fi 802.11 a/b/g/n BT V4.0 LE FM receive |
| GNSS | <ul style="list-style-type: none"> GPS, GLONAS |
| USB | <ul style="list-style-type: none"> 1x USB 2.0 OTG |
| Other Interfaces | <ul style="list-style-type: none"> 3x I2C 1x SPI 1x UART 12x GPIO |
| Operating Voltage Range | <ul style="list-style-type: none"> 5V |
| Temperature Range | <ul style="list-style-type: none"> -30 Deg C to +85 Deg C |
| Form Factor | 82mmx50mm |

RoHS



RoHS Compliant

Module Architecture Diagram

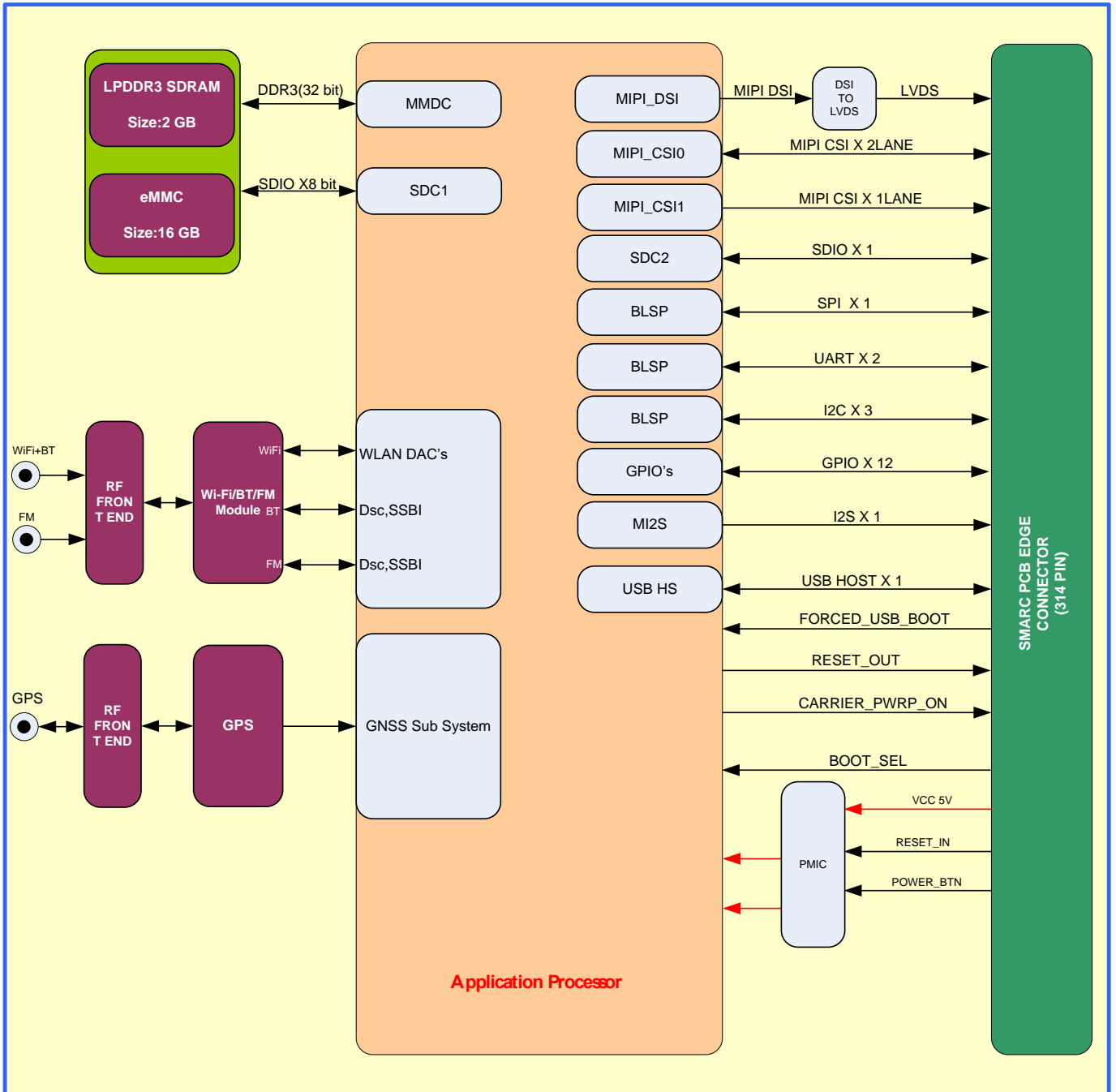


Figure 2: SD210 SOM Block Diagram



Included Software Packages - TESSOLVE Differentiators !

TESSOLVE provides ready to use SDK for evaluation and application development. The section below lists high level details on the included software packages.

- ✓ Board Support Packages (BSP) available for Android
- ✓ Linux Kernel Version: 3.10
- ✓ Operating System :Android(Nougat 7.1)

Ordering Information

| Article | Part No**. | Description |
|----------------------|-------------------------|--|
| MAGIK 2 SMARC Module | M2-SQ2A-4Q1G-2G-16G-C-S | SD210 Quad, 1.3GHz, 2GB RAM, 16GBytes Flash, Commercial Grade, 80mmx52mm |

**Contact TESSOLVE for other possible memory and temperature configurations

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